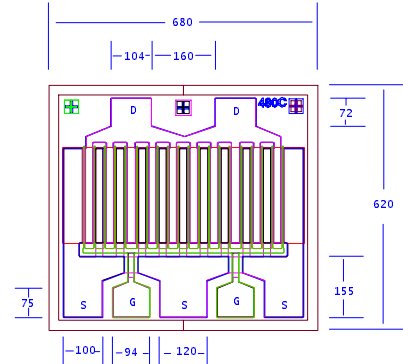


PRELIMINARY DATA SHEET
Low Distortion GaAs Power FET

- **+33.5dBm TYPICAL OUTPUT POWER**
- **18.0dB TYPICAL POWER GAIN AT 2GHz**
- **High BV_{gd} FOR 10V BIAS**
- **0.5 X 4800 MICRON RECESSED “MUSHROOM” GATE**
- **Si₃N₄ PASSIVATION AND PLATED HEAT SINK**
- **ADVANCED EPITAXIAL DOPING PROFILE PROVIDES HIGH POWER EFFICIENCY, LINEARITY AND RELIABILITY**
- **Id_{ss} SORTED IN 80mA PER BIN RANGE**



Chip Thickness: 75 ± 13 microns
All Dimensions In Microns

ELECTRICAL CHARACTERISTICS (T_a = 25 °C)

SYMBOLS	PARAMETERS/TEST CONDITIONS	MIN	TYP	MAX	UNIT
P_{1dB}	Output Power at 1dB Compression V _{ds} =8V, I _{ds} =50% I _{ds}	f= 2GHz 32.0	f= 2GHz 33.5		dBm
		f= 4GHz	33.5		
G_{1dB}	Gain at 1dB Compression V _{ds} =8V, I _{ds} =50% I _{ds}	f= 2GHz 16.0	f= 2GHz 18.0		dB
		f= 4GHz	12.5		
PAE	Gain at 1dB Compression V _{ds} =8V, I _{ds} =50% I _{ds}		f= 2GHz 40		%
I_{ds}	Saturated Drain Current V _{ds} =3V, V _{gs} =0V	640	960	1440	mA
G_m	Transconductance V _{ds} =3V, V _{gs} =0V	200	560		mS
V_p	Pinch-off Voltage V _{ds} =3V, I _{ds} =10mA		-2.5	-4.0	V
BV_{gd}	Drain Breakdown Voltage I _{gd} =4.8mA	-15	-20		V
BV_{gs}	Source Breakdown Voltage I _{gs} =4.8mA	-10	-17		V
R_{th}	Thermal Resistance (Au-Sn Eutectic Attach)		12		°C/W

MAXIMUM RATINGS AT 25°C

SYMBOLS	PARAMETERS	ABSOLUTE ¹	CONTINUOUS ²
V_{ds}	Drain-Source Voltage	14V	10V
V_{gs}	Gate-Source Voltage	-8V	-4.5V
I_{ds}	Drain Current	I _{ds}	960mA
I_{gsf}	Forward Gate Current	120mA	20mA
P_{in}	Input Power	32dBm	@3dB Compression
T_{ch}	Channel Temperature	175°C	150°C
T_{stg}	Storage Temperature	-65/175°C	-65/150°C
P_t	Total Power Dissipation	11.4 W	9.5 W

Note: 1. Exceeding any of the above ratings may result in permanent damage.

2. Exceeding any of the above ratings may reduce MTTF below design goals.

EFC480C

PRELIMINARY DATA SHEET

Low Distortion GaAs Power FET

S-PARAMETERS

10V, 1/2 Idss

Freq GHz	---S11---		---S21---		---S12---		---S22---	
	Mag	Ang	Mag	Ang	Mag	Ang	Mag	Ang
0.500	0.937	-106.2	10.161	120.8	0.022	35.8	0.518	-166.8
1.000	0.897	-134.9	6.389	104.7	0.028	26.4	0.505	-168.3
1.500	0.897	-151.8	4.443	93.5	0.028	21.5	0.524	-171.2
2.000	0.897	-161.0	3.370	85.4	0.029	19.0	0.533	-173.0
2.500	0.898	-167.2	2.695	79.2	0.030	20.2	0.539	-173.8
3.000	0.895	-171.8	2.231	73.9	0.030	19.5	0.542	-174.2
3.500	0.890	-175.4	1.894	69.4	0.030	20.9	0.542	-173.9
4.000	0.850	-176.6	1.654	66.9	0.026	27.6	0.560	-172.2
4.500	0.901	177.7	1.535	59.9	0.032	23.1	0.607	-169.5
5.000	0.899	174.5	1.357	55.2	0.031	25.8	0.617	-170.8
5.500	0.900	172.5	1.208	51.4	0.031	28.1	0.620	-171.8
6.000	0.901	170.8	1.087	48.2	0.031	30.4	0.619	-172.8
6.500	0.902	169.6	0.999	45.8	0.032	32.0	0.616	-172.6
7.000	0.893	168.8	0.941	43.3	0.033	37.1	0.637	-171.2
7.500	0.904	170.7	0.916	39.2	0.037	34.8	0.669	-172.8
8.000	0.919	169.5	0.840	34.2	0.036	35.0	0.681	-175.0
8.500	0.918	169.2	0.783	31.0	0.038	36.6	0.693	-176.9
9.000	0.924	168.7	0.729	27.9	0.037	37.6	0.701	-178.6
9.500	0.927	168.0	0.687	24.5	0.038	39.8	0.706	-179.3
10.000	0.932	167.3	0.647	22.3	0.040	42.4	0.716	179.8

Note: The data included 0.7 mils diameter Au bonding wires:
2 gate wires, 20 mils each; 2 drain wires, 12 mils each; 6 source wires, 7 mils each.